30V N-Channel Enhancement Mode MOSFET

Description

The NP3095G uses advanced trench technology and design to provide excellent $R_{DS(ON)}$ with low gate charge. It can be used in a wide variety of applications.

General Features

- V_{DS} =30V，I_D =95A
  $R_{DS(ON)}$(Typ.)=4.5mΩ @V_{GS}=10V
  $R_{DS(ON)}$(Typ.)=7.1mΩ @V_{GS}=4.5V
  High power and current handing capability
- Lead free product is acquired
- Surface mount package

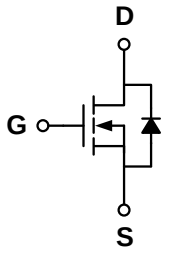
Application

- Load switch

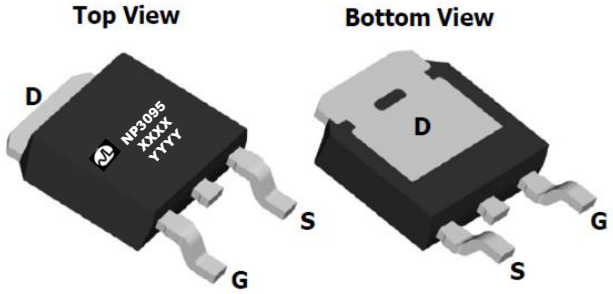
Package

- TO-252-2L

Schematic diagram



Marking and pin assignment



XXXX—Wafer Information
YYYY—Quality Code

Ordering Information

Part Number	Storage Temperature	Package	Devices Per Reel
NP3095G	-55°C to +150°C	TO-252-2L	2500

Absolute Maximum Ratings (TA=25℃ unless otherwise noted)

parameter		symbol	limit	unit
Drain-source voltage		V_{DS}	30	V
Gate-source voltage		V_{GS}	±20	V
Continuous Drain Current	TC=25°C	I_D	95	A
	TC=100°C		72	
Pulsed Drain Current		I_{DP}	200	A
Avalanche Current		IAS	30	A
Avalanche energy(L=0.5mH) (note1)		EAS	112	mJ
Maximum power dissipation	TC=25°C	P_D	85	W
	TC=100°C		44	

Operating junction Temperature range	Tj	-55—150	℃

Electrical Characteristics (TA=25℃ unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
Static Characteristics						
Drain-source breakdown voltage	BV_{DSS}	V_{GS}=0V, I_D=250μA	30	-	-	V
Zero gate voltage drain current	I_{DSS}	V_{DS}=30V, V_{GS}=0V	-	-	1	μA
		T_J=85°C	-	-	30	
Gate Leakage Current	I_{GSS}	V_{DS}=0V, V_{GS}=±20V	-	-	±100	nA
Gate threshold voltage	$V_{GS(th)}$	V_{DS}=V_{GS}, I_D=250μA	1	1.5	2.5	V
Drain-source on-state resistance[1]	$R_{DS(ON)}$	V_{GS}=10V, I_D=20A	-	4.5	5.8	mΩ
		V_{GS}=4.5V, I_D=20A	-	7.1	8.5	
On Status Drain Current	$I_{D(ON)}$	V_{DS}=10V, V_{GS}=10V	95	-	-	A
Diode Characteristics						
Diode Forward Voltage[1]	V_{SD}	I_{SD}=50A,V_{GS}=0V	-	0.8	1.1	V
Diode Continuous Forward Current	I_S		-	95	-	A
Reverse Recovery Time	t_{rr}	I_F=20A, dI/dt=100A/us	-	34	-	ns
Reverse Recovery Charge	Q_{rr}		-	30	-	nC
Dynamic Characteristics[2]						
Gate Resistance	R_G	V_{GS}=0V, V_{DS}=0V,f=1MHz	-	0.65	-	Ω
Input capacitance	C_{ISS}	V_{GS}=0V ,V_{DS}=15V f=1.0MHz	-	2210	-	pF
Output capacitance	C_{OSS}		-	281	-	
Reverse transfer capacitance	C_{RSS}		-	232	-	
Turn-on delay time	$t_{D(ON)}$	V_{GS}=10V, V_{DS}=15V, R_L=20Ω, I_D=1A, R_G=6Ω	-	12	-	ns
Turn-on Rise time	tr		-	14.5	-	
Turn-off delay time	$t_{D(OFF)}$		-	40	-	
Turn-off Fall time	tf		-	15	-	
Total gate charge	Q_g	V_{GS}=10V,I_D=20A V_{DS}=15V	-	42.3		nC
Gate-source charge	Q_{gs}			6.9		
Gate-drain charge	Q_{gd}		-	8.4	-	
Drain-Source Diode Characteristics						
Diode forward voltage	V_{SD}	I_{SD}=20A,V_{GS}=0V	-	0.8	1.2	V

Note: 1：Pulse test; pulse width ≦ 300ns, duty cycle ≦ 2%.

2：Guaranteed by design, not subject to production testing.

Thermal Characteristics

Parameter	Symbol	Typical	Unit
Thermal Resistance-Junction to Case	Rθjc	1.7	℃/W
Thermal Resistance junction-to ambient	Rθja	62.5	

Typical Performance Characteristics

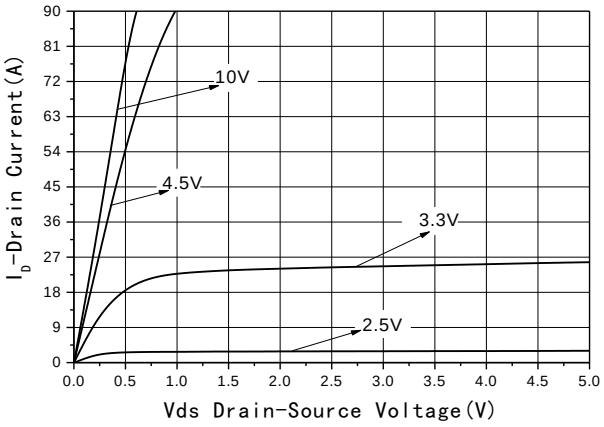


Fig1 Output Characteristics

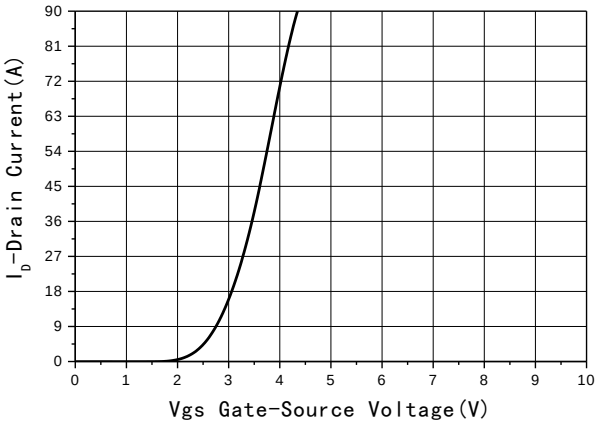


Fig2 Transfer Characteristics

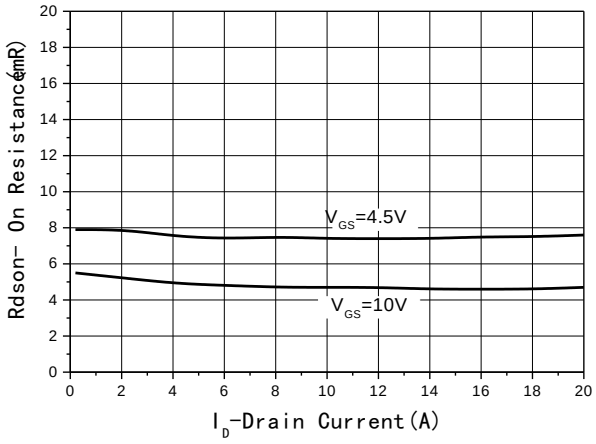


Fig3 Rdson-Drain current

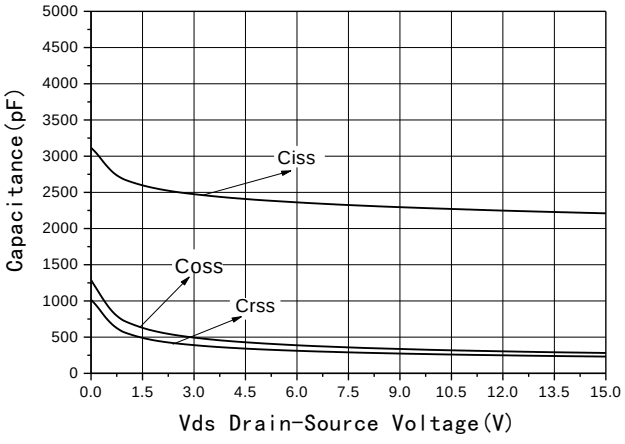


Fig4 Capacitance vs Vds

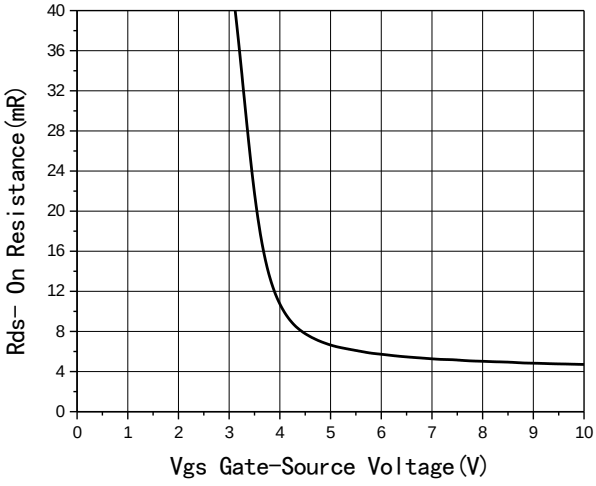


Fig5 Rdson-Gate Drain voltage

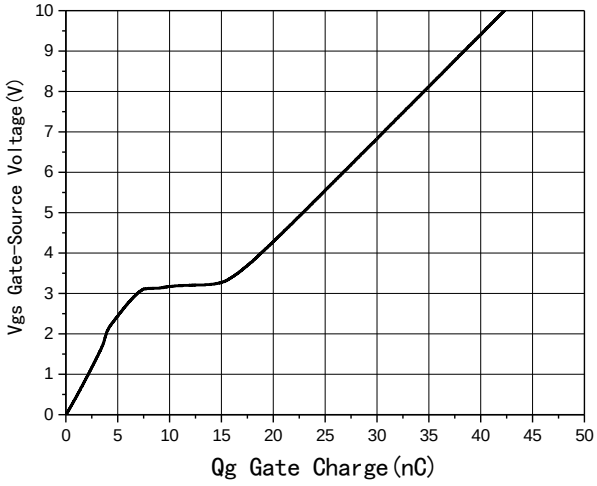


Fig6 Gate Charge

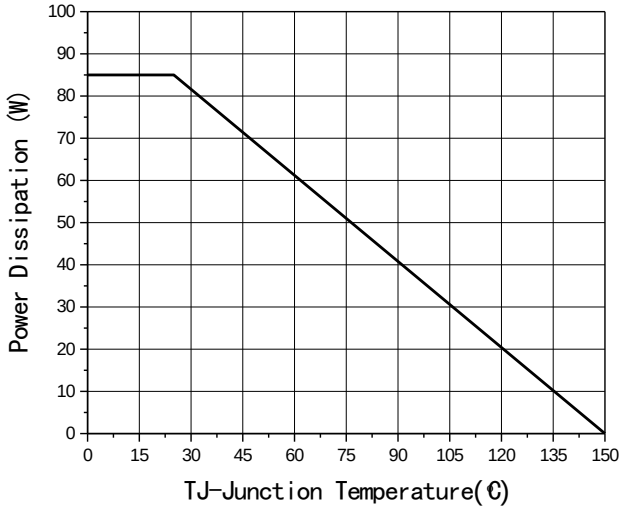


Fig7 Power De-rating

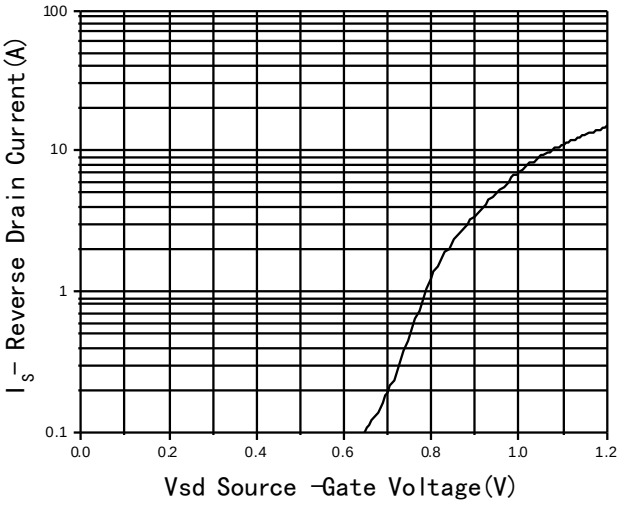
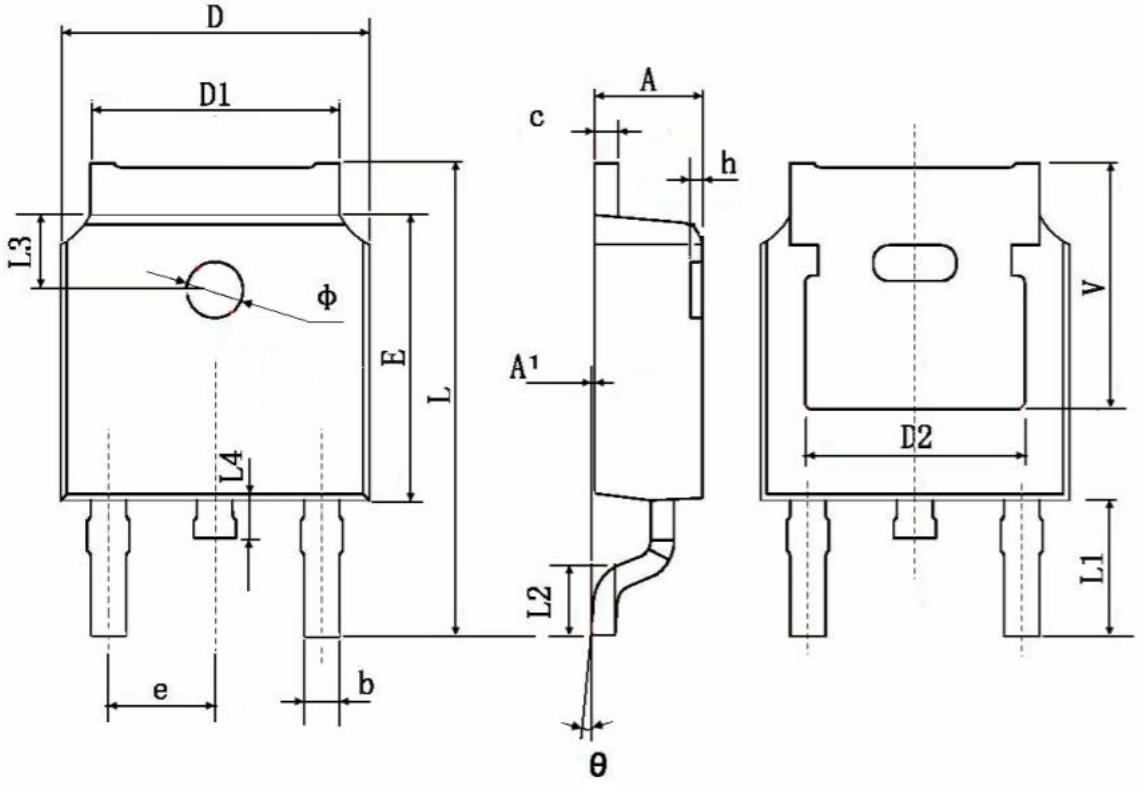


Fig8 Source-Drain Diode Forward

Package Information

- **TO-252-2L**



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	2.200	2.400	0.087	0.094
A1	0.000	0.127	0.000	0.005
b	0.660	0.860	0.026	0.034
c	0.460	0.580	0.018	0.023
D	6.500	6.700	0.256	0.264
D1	5.100	5.460	0.201	0.215
D2	4.830 TYP.		0.190 TYP.	
E	6.000	6.200	0.236	0.244
e	2.186	2.386	0.086	0.094
L	9.800	10.400	0.386	0.409
L1	2.900 TYP.		0.114 TYP.	
L2	1.400	1.700	0.055	0.067
L3	1.600 TYP.		0.063 TYP.	
L4	0.600	1.000	0.024	0.039
Φ	1.100	1.300	0.043	0.051
θ	0°	8°	0°	8°
h	0.000	0.300	0.000	0.012
V	5.350 TYP.		0.211 TYP.	